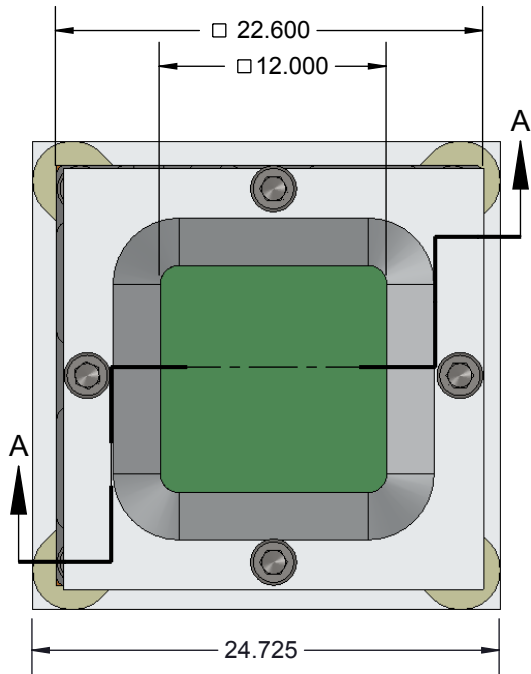


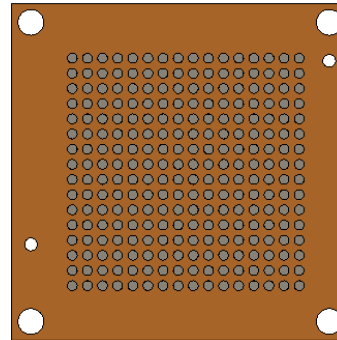
GT BGA Socket - Direct mount, solderless

Features

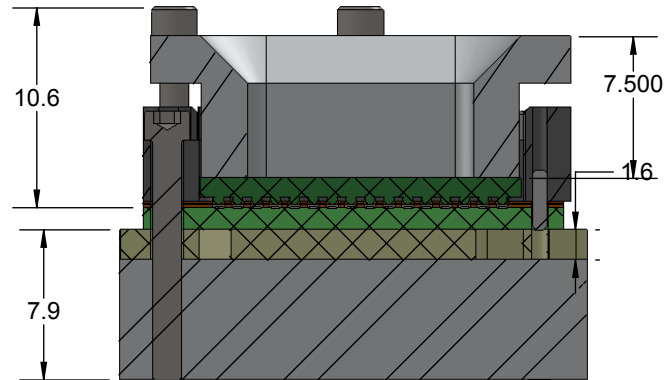
- Directly mounts to target PCB (needs tooling holes) with hardware
- High speed, reliable connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Easily removable swivel socket lid
- Operating temperature range -55C to +160C



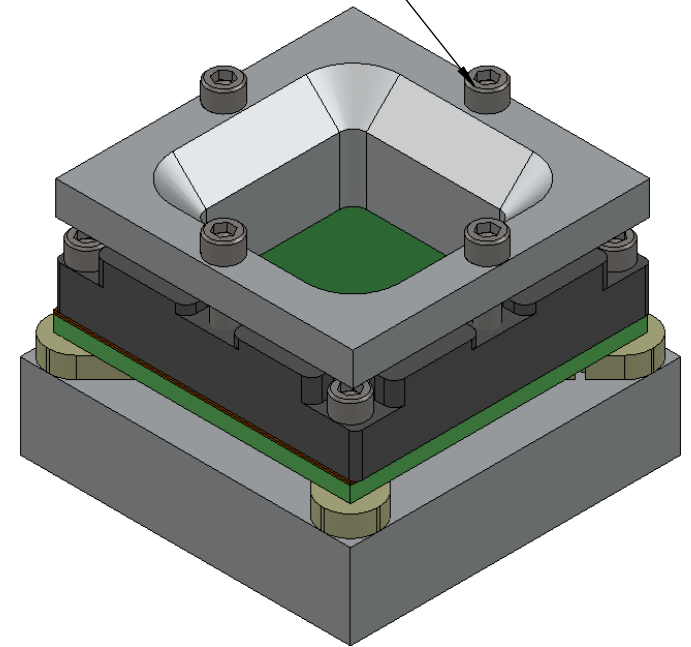
RECOMMENDED TORQUE: 0.5 IN-LBS



GT elastomer



SECTION A-A



Description: GT Open top Socket for 17x17mm 1mm pitch BGA256

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.0254\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.0762\text{mm}$ [$\pm 0.003"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.127\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

GT-BGA-2026 Drawing



Ironwood Electronics, Inc.
Tele: (800) 404-0204
www.ironwoodelectronics.com

Material: N/A
Finish: N/A
Weight: 20.48

STATUS: Released

ENG: V. Panavala

FILE: GT-BGA-2026 Dwg

SHEET: 1 OF 4

DRAWN BY: M. Raske

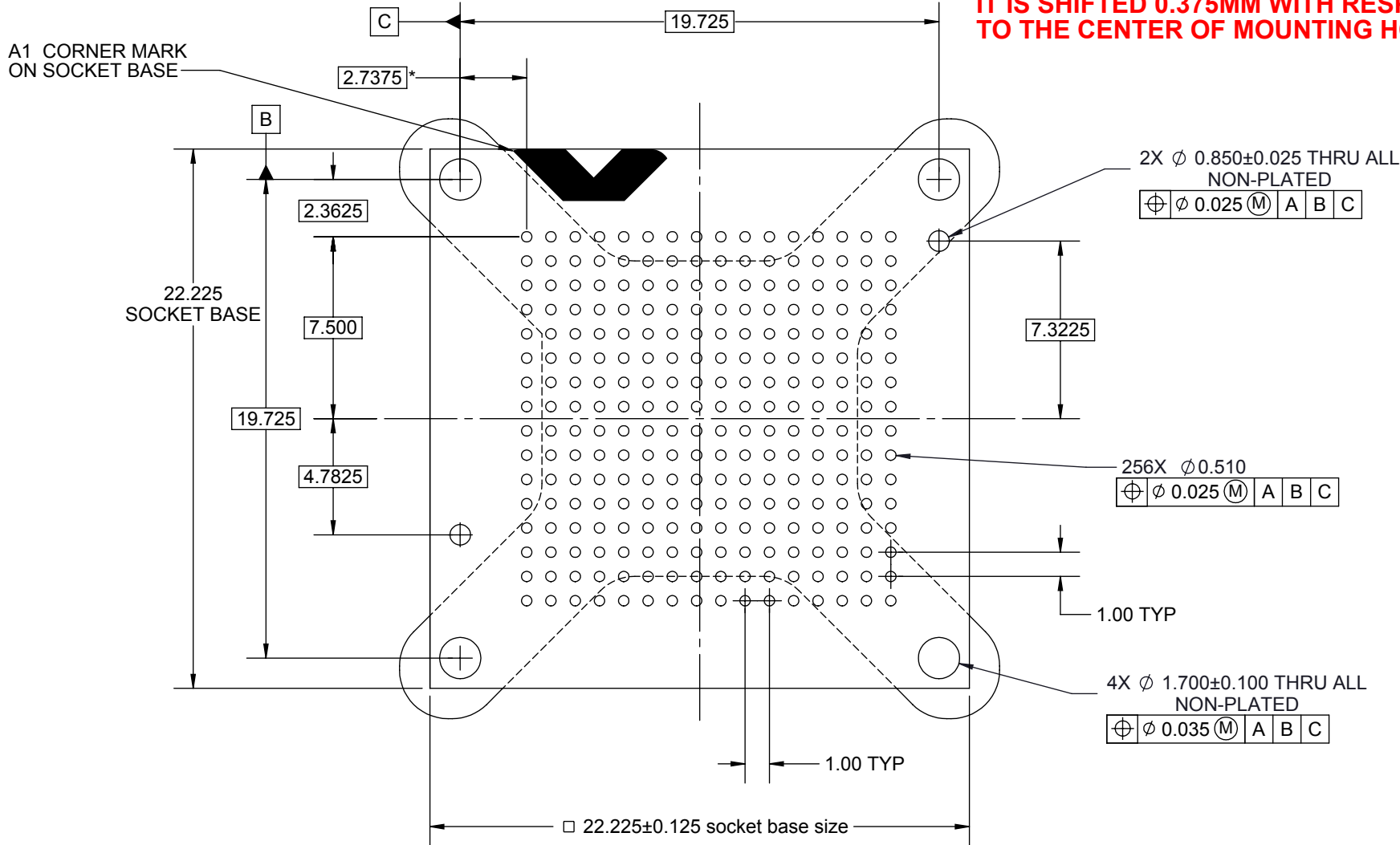
DATE: 06/18/2015

REV. A

SCALE: 5:2

DATUM A IS TOP SIDE OF BOARD

NOTE: PAD LAYOUT IS NOT CENTERED
IT IS SHIFTED 0.375MM WITH RESPECT
TO THE CENTER OF MOUNTING HOLES

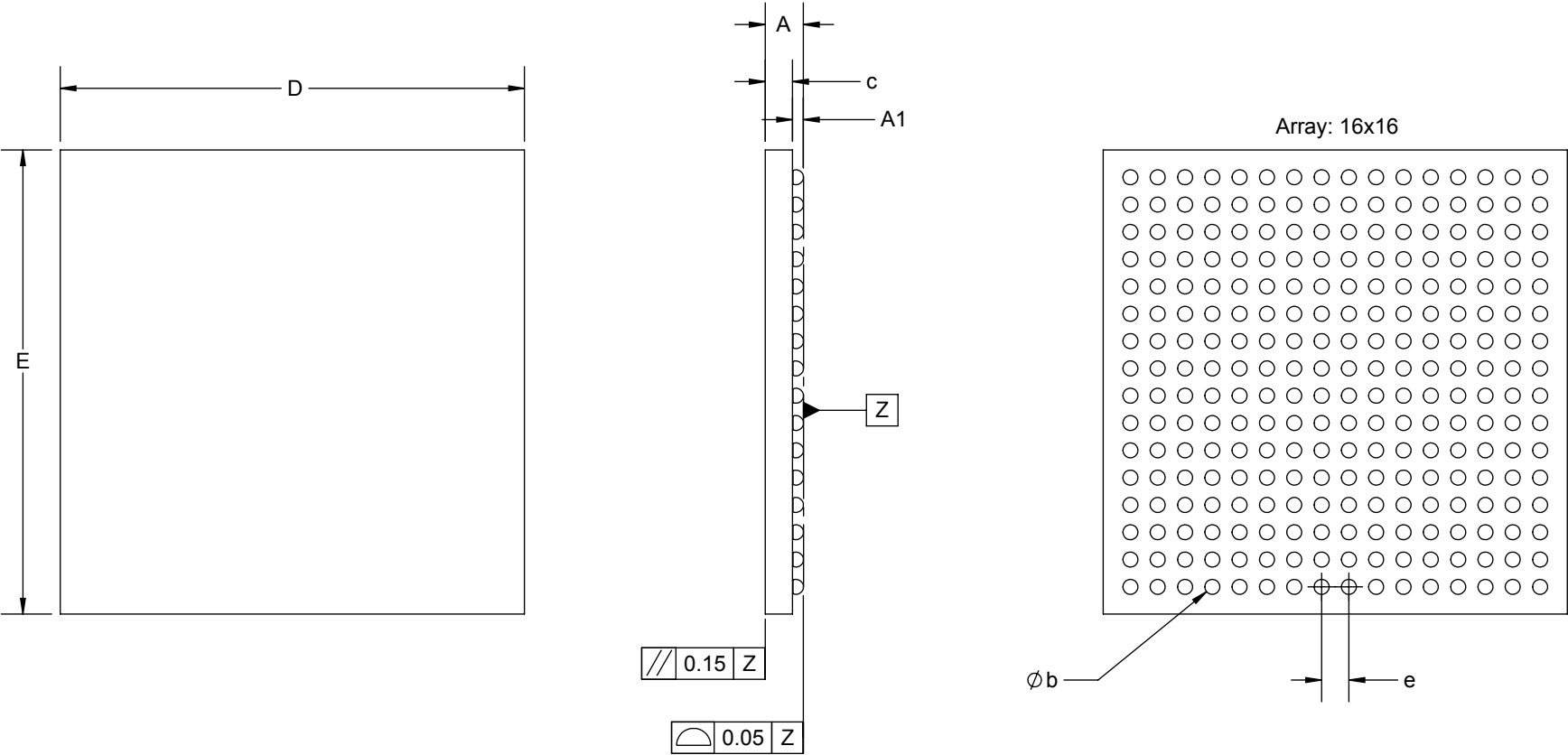


Description: Recommended PCB Layout

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.
Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

Target PCB Recommendations
Total Thickness: 1.6mm min.
Plating: Gold Immersion, Silver Immersion or Solder
PCB Pad Height: same or higher than solder mask

GT-BGA-2026 Drawing		STATUS: Released	SHEET: 2 OF 4	REV. A
	Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	ENG: V. Panavala	DRAWN BY: M. Raske	SCALE: 4:1
		FILE: GT-BGA-2026 Dwg	DATE: 06/18/2015	
		Material: N/A Finish: N/A Weight: 20.48		



1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

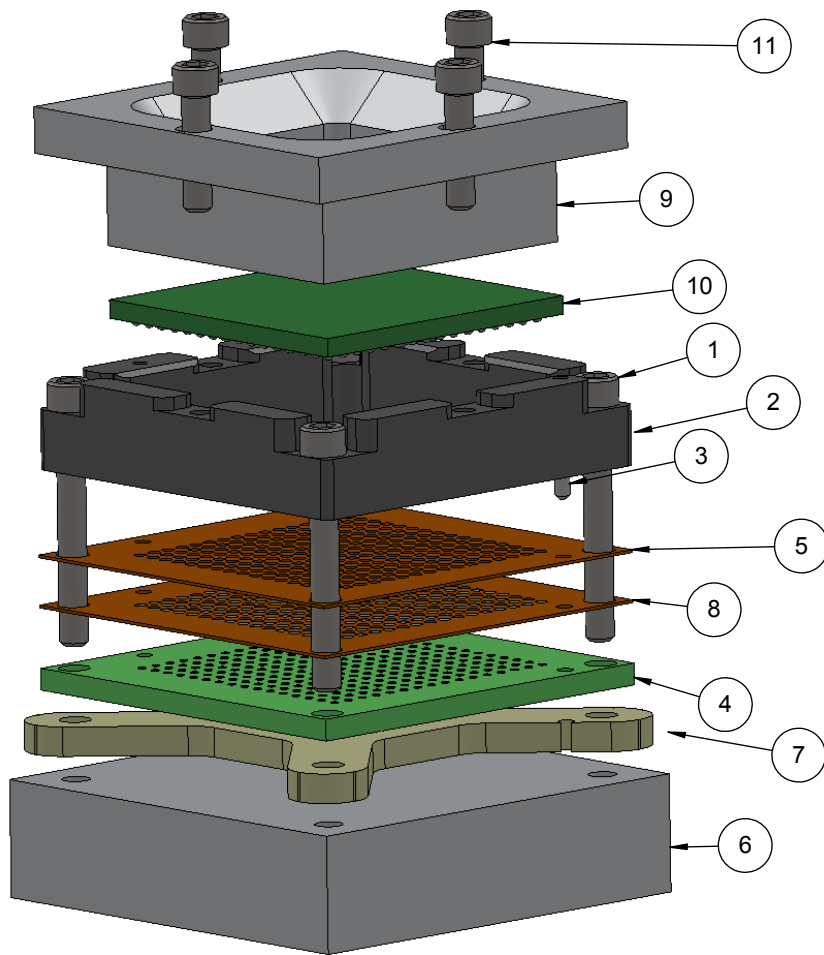
DIM	MIN	MAX
A	1.0	2.0
A1	0.29	0.43
b	0.5	0.6
D	16.8	17.2
E	16.8	17.2
e	1.0	

Description: Compatible Device

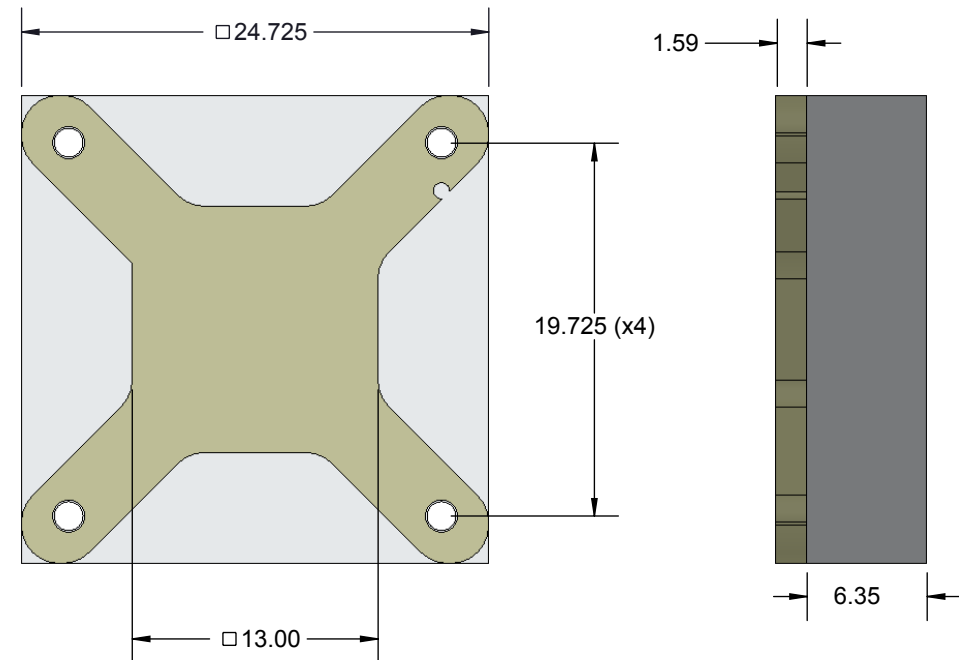
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.
Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

GT-BGA-2026 Drawing		STATUS: Released	SHEET: 3 OF 4	REV. A
	Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	ENG: V. Panavala	DRAWN BY: M. Raske	SCALE: 4:1
		FILE: GT-BGA-2026 Dwg	DATE: 06/18/2015	

Material: N/A
Finish: N/A
Weight: 20.48



ITEM NO.	DESCRIPTION	Material
1	Mounting Screw	Stainless Steel
2	Socket Base	Aluminum Alloy
3	Dowel Pin	Stainless Steel
4	Target PCB	High Temp FR4
5	Ball Guide; BGA256, 16x16 arr 1mm pitch 0.375 offset	Kapton Polyimide/Cirlex
6	Backing Plate	Aluminum Alloy
7	Insulation Plate for 17x17mm IC	FR4 Standard
8	GT Elastomer 17x17mm IC 1mm pitch 16x16 array	Conductive Elastomer
9	Socket Lid/Compression Plate	7075-T6 Aluminum Alloy
10	TEST CHIP	High Temp FR4
11	#0-80 X .25 LG, SOC HD CAP SCREW, ALLOY STL, BLK OXIDE	Alloy Steel



Description: Socket, Backing Plate Detail

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

INSULATION AND BACKING PLATE DETAIL

GT-BGA-2026 Drawing		STATUS: Released	SHEET: 4 OF 4	REV. A
 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A	ENG: V. Panavala	DRAWN BY: M. Raske	SCALE: 5:2
	Finish: N/A	FILE: GT-BGA-2026 Dwg	DATE: 06/18/2015	
	Weight: 20.48			